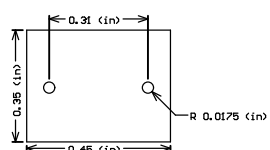
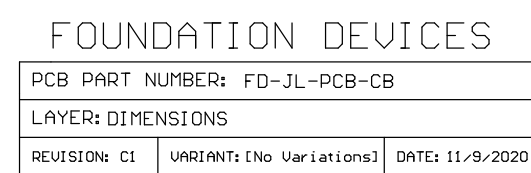


NOTES: (UNLESS OTHERWISE SPECIFIED)

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED CIRCUIT BOARD IN ACCORDANCE WITH SPECIFICATION IPC-6012 CLASS 2 (LATEST REVISION).
2. THE PCB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 260 DEGREES CELSIUS FOR 10 SECONDS.
3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101E/124 or /129
 - TG - MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.
 - TD - MUST BE GREATER THAN OR EQUAL TO 325 DEGREES CELSIUS.
4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'
5. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE 0.1mm/0.1mm
6. PLATING FINISH: ENIG
7. SOLDERMASK - TO MEET THE REQUIREMENTS OF IPC-SM-840E (OR LATEST REVISION).
 - BLACK COLOR. BOTH SIDES.
 - SOLDERMASK ON SOLDERABLE SURFACES IS PROHIBITED.
 - ALL CIRCUITRY DEFINED AS COVERED SHALL NOT BE EXPOSED.
8. SILKSCREEN - WHITE EPOXY OR ACRYLIC INK. BOTH SIDES. NO SILKSCREEN ON ANY EXPOSED COPPER FEATURE.
9. REMOVE ALL NON-FUNCTIONAL INNER LAYER PADS.
10. ELECTRICAL TEST - 100% IPCD356.
11. DFM CHECK MUST BE RUN ON BOARD DATA BEFORE BUILDING BOARDS.
 - UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY FOUNDATION.
12. TEARDROPS MAY BE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.
13. VIA TENTING - ALL VIAS ON BOTH SIDES MUST HAVE TENTING
14. FINISHED PCB THICKNESS IS CRITICAL: FROM L1 PAD TO L2 PAD TO BE 0.8mm +/- 10%
15. TWO SOLDER SAMPLES TO BE PROVIDED
16. SUPPLIER MARKINGS - ON SECONDARY SIDE ONLY.
 - MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94U-0

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
C1	Release for Production	11/09/2020	M. Beach



Layer Stack-Up (Detail A)			
Layer Name	Gerber Document	Copper Thickness	Insulator Thickness
(.GTS)			
T1 0.5oz Plated Copper Foil	(.GTL)	2.0mil	3.34mil
L2 1.0oz Copper	(.G1)	1.3mil	18.72mil
L3 1.0oz Copper	(.G2)	1.3mil	3.34mil
L4 0.5oz Plated Copper Foil	(.GBL)	2.0mil	
Bottom Solder Mask (.GBS)			
Total Board Thickness:		32mil	

LICENCE: CERN-OHL-S v2

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DRAWN BY M. Beach	FOUNDATION		Foundation Devices Inc. 6 Liberty Square #6018 Boston, MA 02109	
CHECKED BY 11/09/2020	PCB PART NUMBER: FD-JL-PCB-CB			
APPROVED BY 11/09/2020	SIZE C	DATE: 11/9/2020	VARIANT: [No Variations]	REV C1
	SCALE: 1/1	DO NOT SCALE DRAWING	SHEET 1 OF 1	